

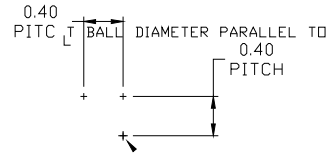
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

WLCSP10 0.77x2.27x0.33
CASE 567YK
ISSUE A

ON Semiconductor®



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A		0.33	0.35
A1	0.034	0.040	0.046
A2	0.2525	0.265	0.2775
A3	0.025 REF		
b	0.15	0.17	0.19
D	0.720	0.770	0.820
E			
e	0.40 BSC		



BOTTOM V

For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.